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Zener Diode

Panasonic DZ4J056K0R

DZ4J056K0R

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

■ Features

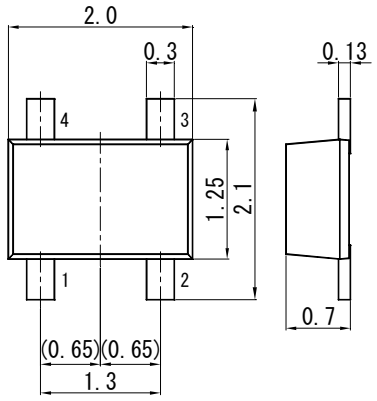
- Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: DJ

■ Basic Part Number :
Dual DZ2J056 (Parallel)

■ Packaging
Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

Unit: mm



1. Anode-1
2. Anode-2
3. Cathode-2
4. Cathode-1

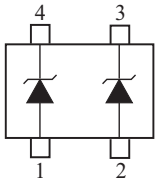
Panasonic	SMini4-F3-B
JEITA	SC-113BB
Code	—

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	200	mW
Electrostatic discharge *2	ESD	±15	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)
Solder in (0.8 mm x 0.8 mm)
*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

Internal Connection



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	5.32		5.88	V
Zener operating resistance	RZ	IZ = 5 mA			40	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω
Reverse current	IR	VR = 2.5 V			0.5	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		1.6		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
2. Absolute frequency of input and output is 5 MHz.
3. *1: The temperature must be controlled 25 °C for VZ mesurement.
VZ value measured at other temperature must be adjusted to VZ (25 °C)
*2: VZ guaranted 20 ms after current flow.
*3: Tj = 25 °C to 150 °C

Established : 2009-12-11
Revised : 2013-10-04

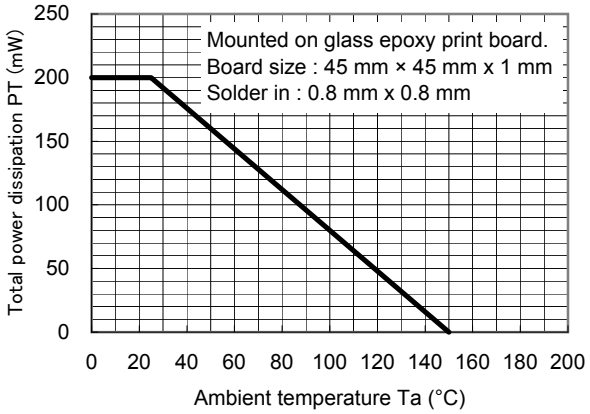
Panasonic

Zener Diode

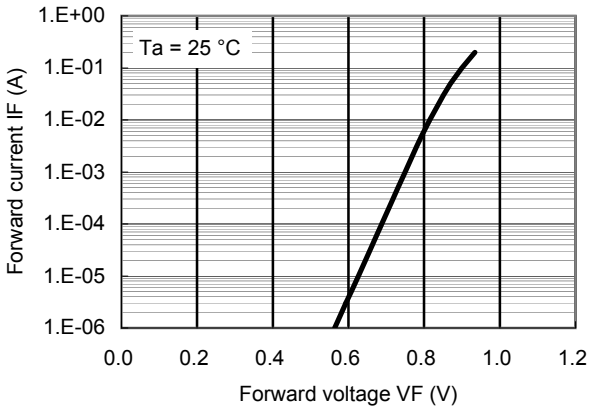
DZ4J056K0R

Technical Data (reference)

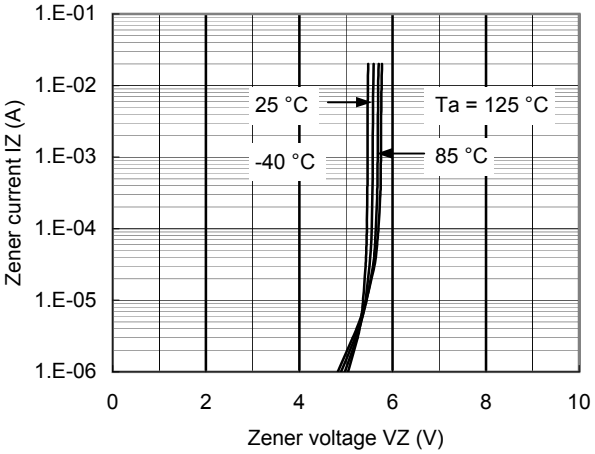
PT - Ta



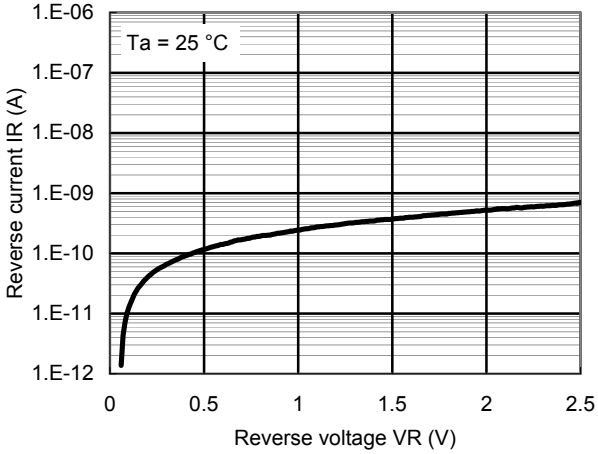
IF - VF



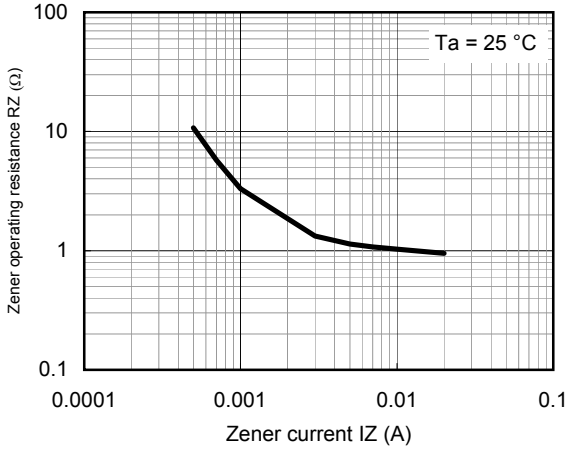
IZ - VZ



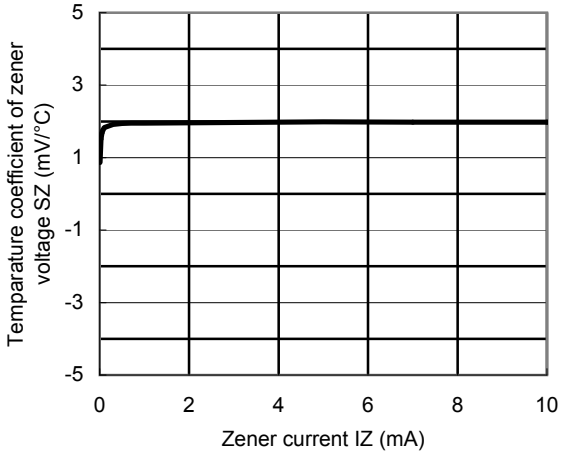
IR - VR



RZ - IZ



SZ - IZ



Established : 2009-12-11
Revised : 2013-10-04

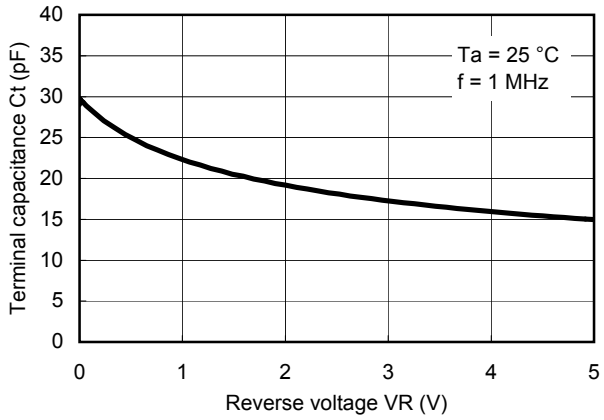
Panasonic

Zener Diode

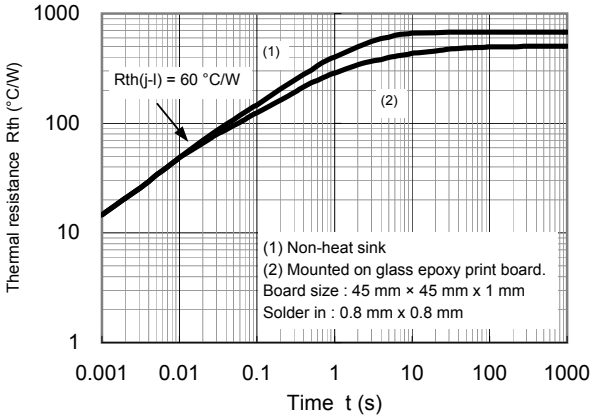
DZ4J056K0R

Technical Data (reference)

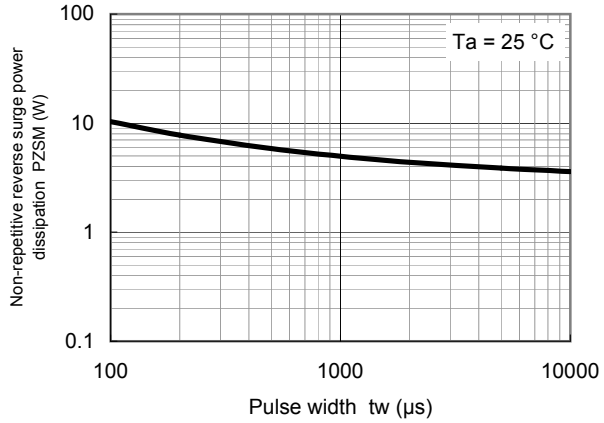
Ct - VR



Rth - t



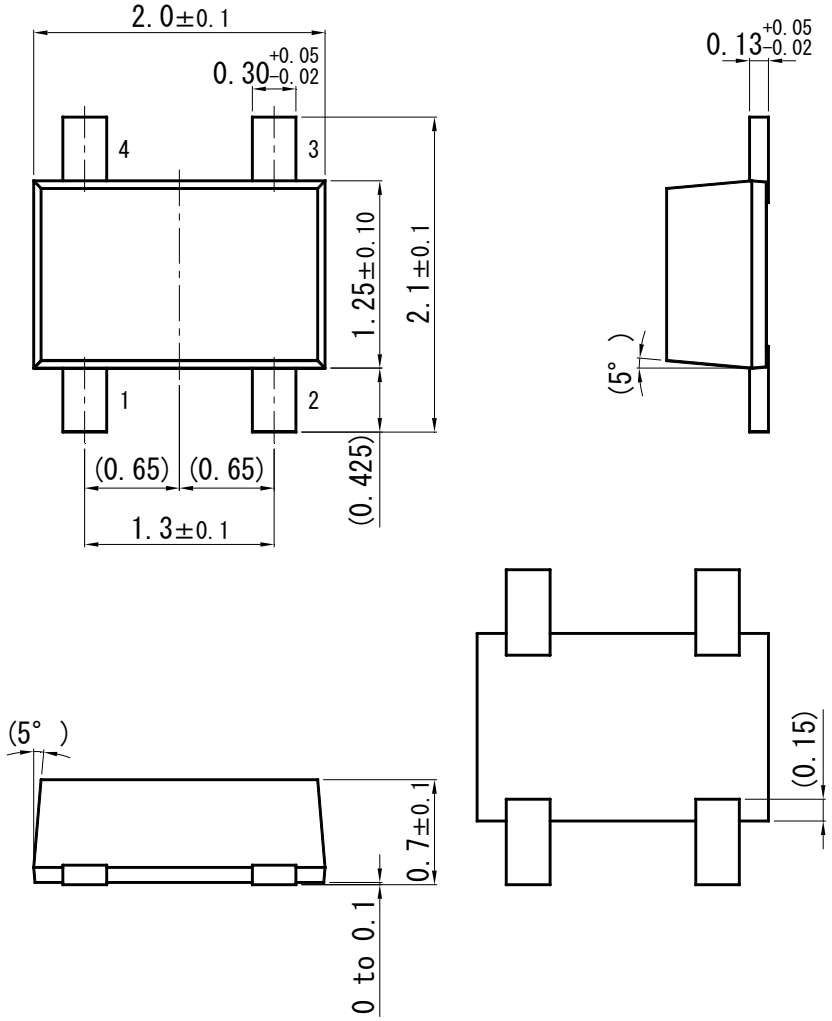
PZSM - tw



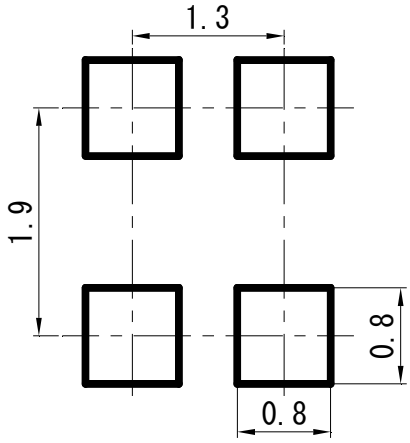
Established : 2009-12-11
Revised : 2013-10-04

SMini4-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



Established : 2009-12-11
Revised : 2013-10-04

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